

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHINYA WATANABE	06/11/2014
KAZUYUKI HIGASHI	06/11/2014
TAKU KAMOTO	06/11/2014
RECEIVING PARTY DATA	
Name:	KABUSHIKI KAISHA TOSHIBA
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State/Country:	JAPAN
Postal Code:	105-8001
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14317648
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Correspondent Name:	HOLTZ, HOLTZ, GOODMAN & CHICK PC
Address Line 1:	220 FIFTH AVENUE
Address Line 2:	16TH FLOOR
Address Line 4:	NEW YORK, NEW YORK 10001-7708
ATTORNEY DOCKET NUMBER:	14202
NAME OF SUBMITTER:	AMIT KULKARNI
SIGNATURE:	/ak/
DATE SIGNED:	06/27/2014
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 3	
source=14202_Declaration_Assignment#page1.tif	
source=14202_Declaration_Assignment#page2.tif	

Combined Declaration and Assignment for Utility or Design Application

Title of Invention	METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE AND SEMICONDUCTOR INTEGRATED CIRCUIT WAFER
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As the below named inventor, I hereby declare that:

This declaration is directed to: The attached application, or
 United States application or PCT international application number _____ filed on _____.

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

In consideration of value received, I sell and assign to Kabushiki Kaisha Toshiba, having a business address at 1-1, Shibaura 1-chome, Minato-ku, Tokyo 105-8001 Japan, its successors, assigns or nominees, hereinafter referred to as "Assignee", my entire right, title and interest in and to said invention, and in and to all applications for patent and patents for said invention, in all countries of the world, including all divisions, reissues, continuations, substitutions and extensions thereof and all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of intellectual property, including rights of priority, resulting from the filing of any of said applications.

I authorize said Assignee to file and prosecute an application or applications for patent for said invention as the applicant, and I request any official whose duty it is to issue patents, to issue any patent on said invention to said Assignee.

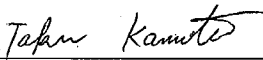
I agree that on request and without further consideration, but at the expense of said Assignee, I will communicate to said Assignee or its representatives all facts known to me respecting said invention and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue, or other applications, make all rightful oaths and declarations, and generally do everything possible to aid said Assignee to obtain and enforce proper patent protection for said invention in all countries.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

LEGAL NAME OF INVENTOR		
Shinya WATANABE	<i>Shinya Watanabe</i>	<i>June 11, 2014</i>
Inventor (printed name)	Signature	Date

Holtz, Holtz, Goodman & Chick PC
 220 Fifth Avenue, 16th Floor, New York, NY 10001-7708
 Tel. (212) 319-4900 Fax. (212) 319-5101

Combined Declaration and Assignment for Utility or Design Application

Title of Invention	METHOD OF MANUFACTURING A SEMICONDUCTOR DEVICE AND SEMICONDUCTOR INTEGRATED CIRCUIT WAFER	
As the below named inventor, I hereby declare that:		
This declaration is directed to:	<input checked="" type="checkbox"/> The attached application, or <input type="checkbox"/> United States application or PCT international application number _____ filed on _____.	
The above-identified application was made or authorized to be made by me.		
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.		
<p>In consideration of value received, I sell and assign to <u>Kabushiki Kaisha Toshiba</u>, having a business address at <u>1-1, Shibaura 1-chome, Minato-ku, Tokyo 105-8001 Japan</u>, its successors, assigns or nominees, hereinafter referred to as "Assignee", my entire right, title and interest in and to said invention, and in and to all applications for patent and patents for said invention, in all countries of the world, including all divisions, reissues, continuations, substitutions and extensions thereof and all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of intellectual property, including rights of priority, resulting from the filing of any of said applications.</p>		
I authorize said Assignee to file and prosecute an application or applications for patent for said invention as the applicant, and I request any official whose duty it is to issue patents, to issue any patent on said invention to said Assignee.		
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LEGAL NAME OF INVENTOR		
Taku KAMOTO		<i>June 11, 2019</i>
Inventor (printed name)	Signature	Date

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